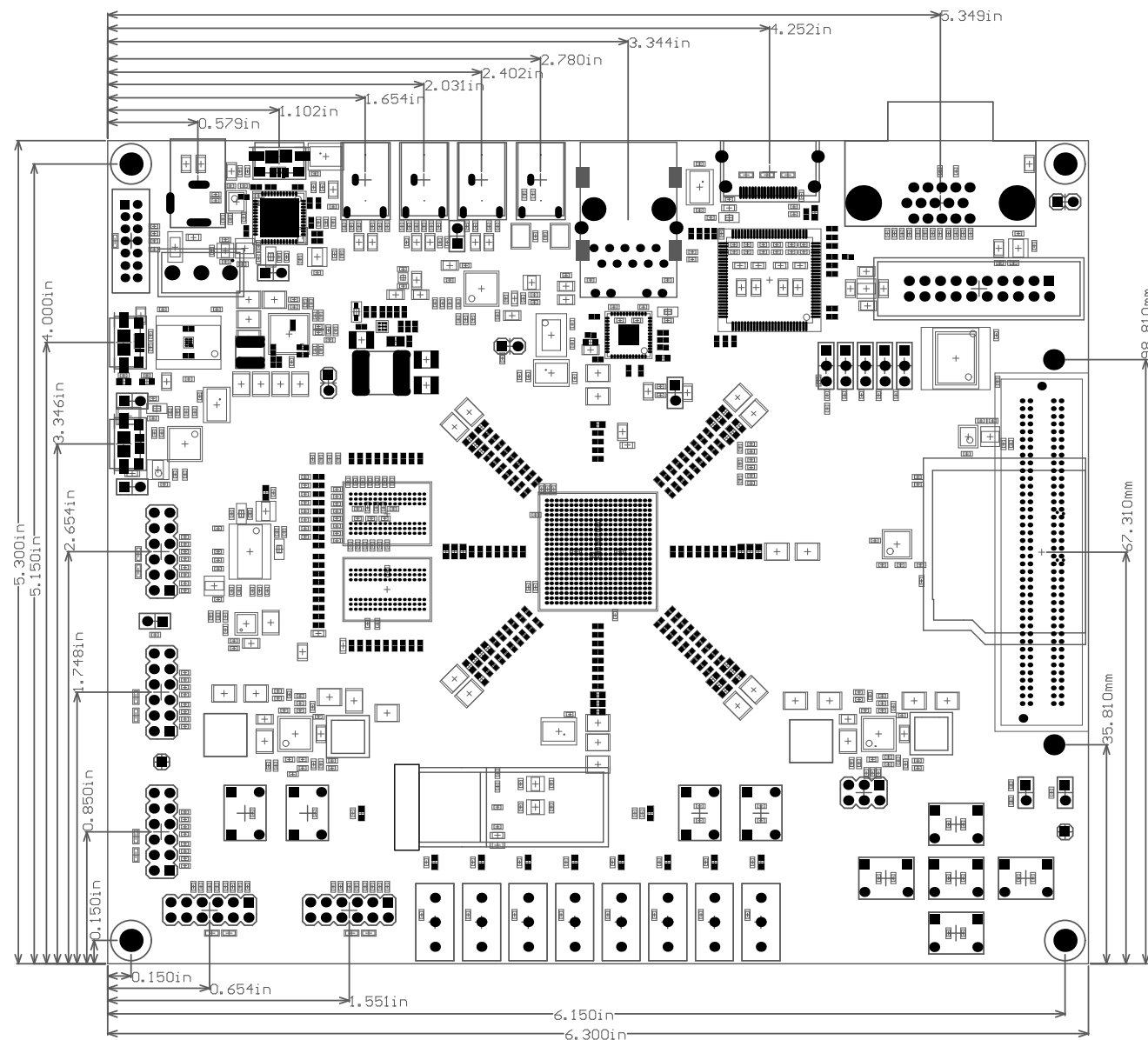


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## Layer Stack Up Detail for: ZED.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.0102mm	Solder Resist	3.50	
Top Layer	(.GTL)	0.0356mm	0.1mm	FR-4	4.80	Core
GND2	(.GP1)	0.0356mm	0.125mm	FR-4	4.80	PrePreg
Mid-Layer 1	(.G1)	0.017mm	0.125mm	FR-4	4.80	Core
Mid-Layer 2	(.G2)	0.017mm	0.125mm	FR-4	4.80	PrePreg
POWER1	(.GP2)	0.0356mm	0.125mm	FR-4	4.80	PrePreg
POWER2	(.GP3)	0.0356mm	0.35mm	FR-4	4.80	Core
MidLayer3	(.G3)	0.017mm	0.125mm	FR-4	4.80	Core
Mid-Layer 4	(.G4)	0.017mm	0.125mm	FR-4	4.80	PrePreg
GND7	(.GP4)	0.0356mm	0.125mm	FR-4	4.80	PrePreg
Bottom Layer	(.GBL)	0.0356mm	0.1mm	FR-4	4.80	Core
Bottom Solder Mask	(.GBS)		0.0102mm	Solder Resist	3.50	